

Title (en)

A METHOD FOR FABRICATING A FLEXIBLE ORGANIC LIGHT EMITTING DIODE USING A PRESSURE SENSITIVE ADHESIVE COMPOSITION

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER FLEXIBLEN ORGANISCHEN LICHEMITTIERENDEN DIODE MITTELS EINER DRUCKEMPFLINDLICHEN KLEBSTOFFZUSAMMENSETZUNG

Title (fr)

MÉTHODE DE FABRICATION D'UNE DIODE ÉLECTROLUMINESCENTE ORGANIQUE FLEXIBLE À UTILISER UNE COMPOSITION ADHÉSIVE SENSIBLE À LA PRESSION

Publication

EP 3645651 B1 20230906 (EN)

Application

EP 18797382 A 20181017

Priority

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Abstract (en)

[origin: WO2019079366A1] A pressure sensitive adhesive composition can cure via hydrosilylation to form a pressure sensitive adhesive. The pressure sensitive adhesive composition may be coated on a substrate and cured to form a protective film. The protective film is useful in flexible OLED device fabrication processes, e.g., for protection of passivation layers.

IPC 8 full level

C09J 183/04 (2006.01); **C09J 7/38** (2018.01)

CPC (source: EP KR US)

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